

CXG1122EN

DESCRIPTION

The CXG1122EN is one of a range of **low insertion loss**, high power MMIC antenna switches for GSM / GPRS Tripleband, Dualband (CXG1121TN) and applications. The low insertion loss on transmit means **increased talk time** as the Tx power amplifier can be operated at a lower output level. **On chip logic** reduces component count and **simplifies PCB layout** by allowing direct connection of the switch to digital baseband control lines with **CMOS logic levels**.

This switch is an **SP5T**, one antenna can be routed to either of the 2 Tx or 3 Rx ports. It requires 3 CMOS control lines (CTL1, CTL2 and Tx ON).

The **Sony GaAs JFET** process is used for low insertion loss. An evaluation PCB is available.

Features

- Insertion Loss (Tx) 0.5dB typical at 34dBm (GSM 900)
- 3 CMOS compatible Control Lines
- Low second harmonic, -40dBm typical, at 34dBm (GSM 900)
- Small package Size: VSON-16 pin (2.7mm x 3.5mm x 0.9mm)

APPLICATIONS

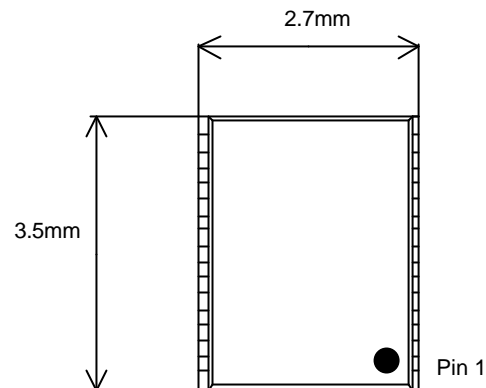
Triple-band Handsets using combinations of

- GSM900 / DCS1800 / PCS1900
- GPRS
- DECT

STRUCTURE

GaAs J-FET MMIC

GaAs MMIC's are ESD sensitive devices. Special handling precautions are required.



VSON-16P-01

Pin Pitch 0.4mm

SONY ^â SP5T GSM TRIPLE-BAND / GPRS ANTENNA SWITCH

Truth Table

On Path	CTL1	CTL2	Tx ON
ANT – Tx1 GSM 900	H	Don't Care	H
ANT – Tx2 DCS 1800 & PCS 1900	L	Don't Care	H
ANT – Rx1 GSM 900/DCS1800/PCS 1900	H	L	L
ANT – Rx2 GSM 900/DCS1800/PCS 1900	L	L	L
ANT – Rx3 GSM 900/DCS1800/PCS 1900	L	H	L

Other frequency assignments upon request. See last page for contact details.

Electrical Characteristics

(Tamb= +25°C)

	Symbol	Path	Condition	Min.	Typ.	Max.	Unit
Insertion Loss	IL	Tx1,Tx2-Ant	*1		0.5	0.7	dB
		Tx1,Tx2 -Ant	*2		1.0	1.2	dB
		Rx1 -Ant	*3		0.65	0.85	dB
		Rx2 -Ant	*4		1.2	1.4	dB
		Rx3 -Ant	*5		1.2	1.4	dB
Isolation	ISO.	Ant-Tx1,Tx2	*3	18	20		dB
			*4, *5	14	16		dB
		Tx-Rx1,Rx2,Rx3	*1	23	25		dB
			*2	18	20		dB
VSWR	VSWR			1.2			
Harmonics*** (see note below)	2fo	Tx1,Tx2-Ant	*1, *2		-40	-36	dBm
	3fo				-34	-30	dBm
P _{1dB} Compression Input Power	P _{1dB}	Tx1,Tx2-Ant	*1, *2		36		dBm
Control Current	I _{ctl}		V _{ctl} = 3.0 V		80	120	μ A
Supply Current for Tx and Rx modes	I _{Tx/ Rx}		V _{dd} = 3.3V		0.3	1	mA

Electrical Characteristics are measured with all RF ports terminated in 50 Ohms.

*** Harmonics measured with Tx inputs harmonically matched. We recommend the use of harmonic matching to ensure optimum performance.

* 1 Power incident on GSM Tx, Pin =34dBm, 880 to 915 MHz, V_{dd}=3.3V, GSM Tx enabled

* 2 Power incident on DCS/PCS Tx, Pin =32dBm, 1710 to 1910 MHz, V_{dd}=3.3V, DCS/PCS Tx enabled

* 3 Power incident on Ant, Pin =10dBm, 925 to 960 MHz, V_{dd}=3.3V, GSM Rx enabled

* 4 Power incident on Ant, Pin = 10dBm, 1805 to 1880 MHz, V_{dd}=3.3V, DCS Rx enabled

* 5 Power incident on Ant, Pin =10dBm, 1930 to 1990 MHz, V_{dd}=3.3V, PCS Rx enabled

SONY [®] SP5T GSM TRIPLE-BAND / GPRS ANTENNA SWITCH

Supply voltage value (Vdd):

Mode	Minimum	Typical	Maximum
GSM/DCS Tx	3.0V	3.3V	3.5V
GSM/DCS/PCS Rx	2.7V	3.0V	3.5V

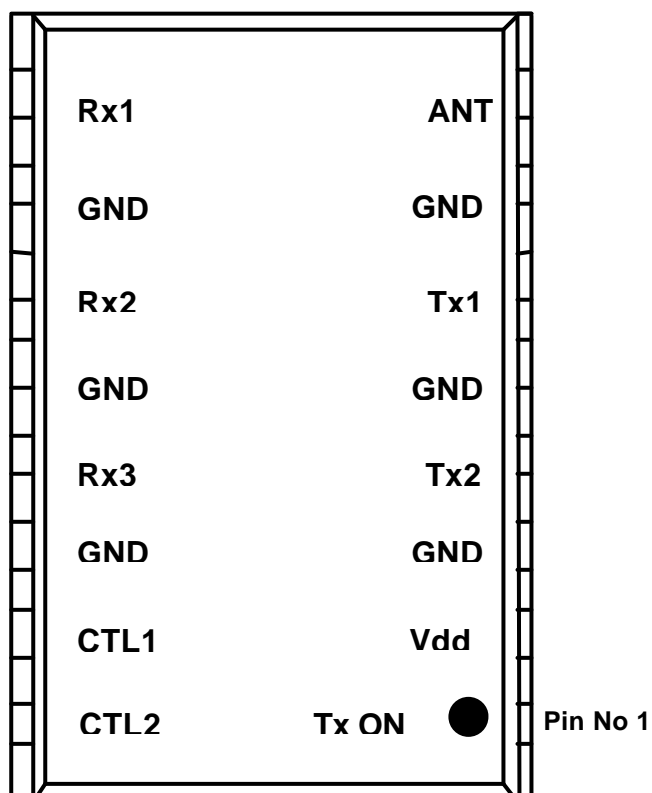
CMOS logic value:

	Minimum	Typical	Maximum
High	2.4V	2.8V	3.2V
Low	0V		0.4V

Absolute Maximum Ratings (Ta = 25°C)

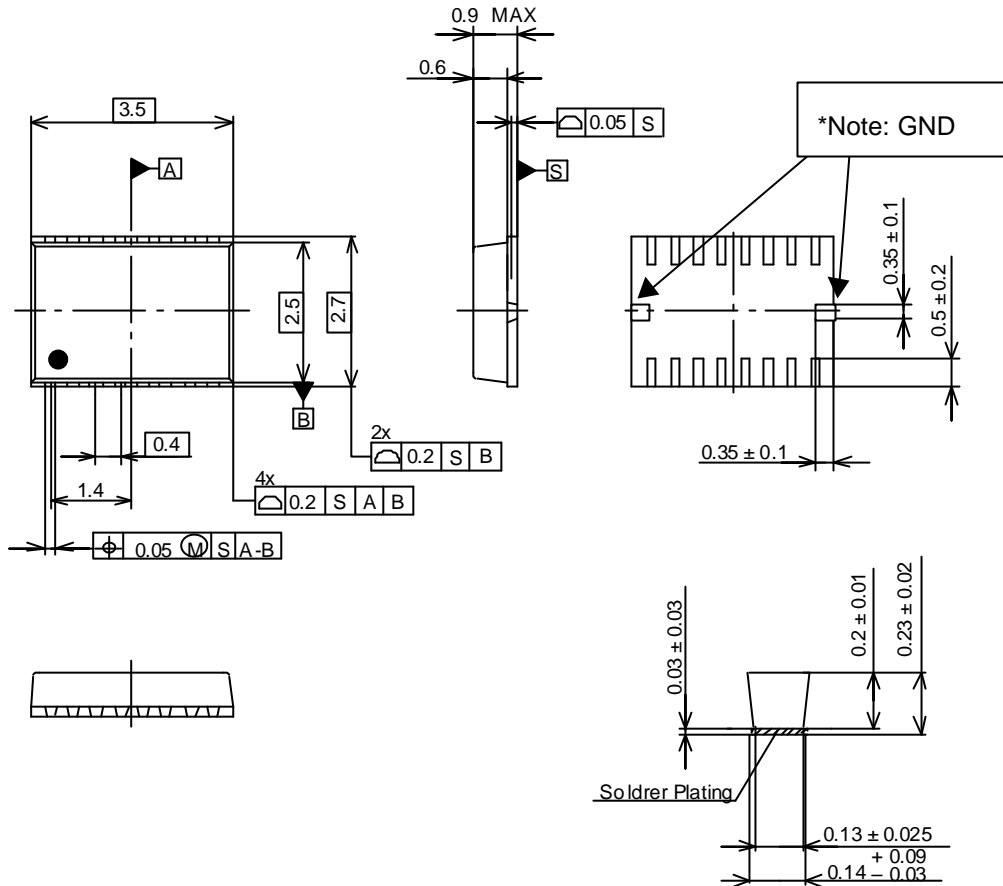
- Bias Voltage Vdd 7V
- Control Voltage Vctl 5V
- Operating Temperature -20°C to +80°C

Pin Out



Package Outline Drawing

16PIN VSON(PLASTIC)



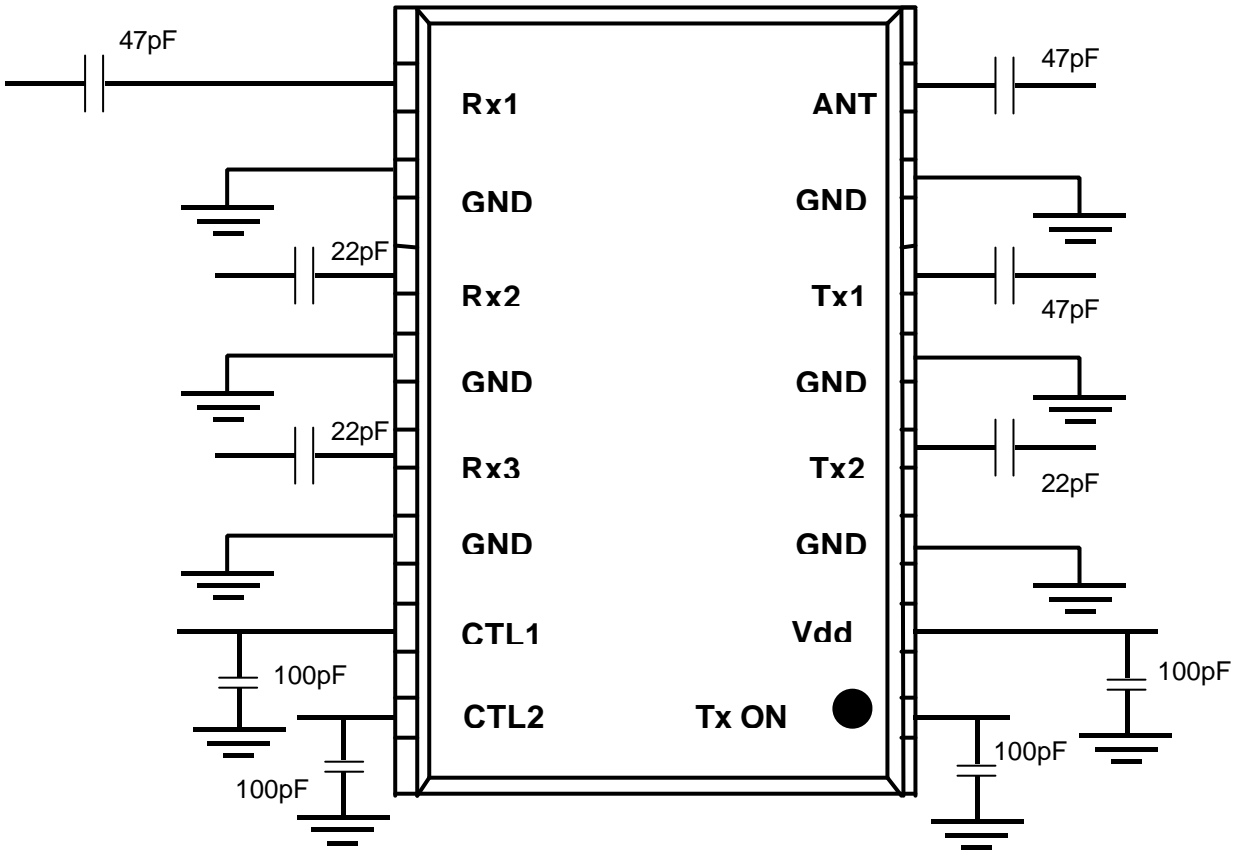
NOTE: 1) The dimensions of the terminal section apply to the ranges of 0.1mm and 0.25mm from the end of a terminal.

TERMINAL SECTION

PACKAGE STRUCTURE

SONY CODE	VSON-16P-01	PACKAGE MATERIAL	EPOXY RESIN
EIAJ CODE	_____	LEAD TREATMENT	SOLDER PLATING
JEDEC CODE	_____	LEAD MATERIAL	COPPER ALLOY
		PACKAGE MASS	0.02 g

DC Blocking Capacitors and Decoupling Capacitors



Note: Capacitors are required on all RF ports for DC blocking (22pF – 47pF). Decoupling capacitors are required on Vdd and on control lines.

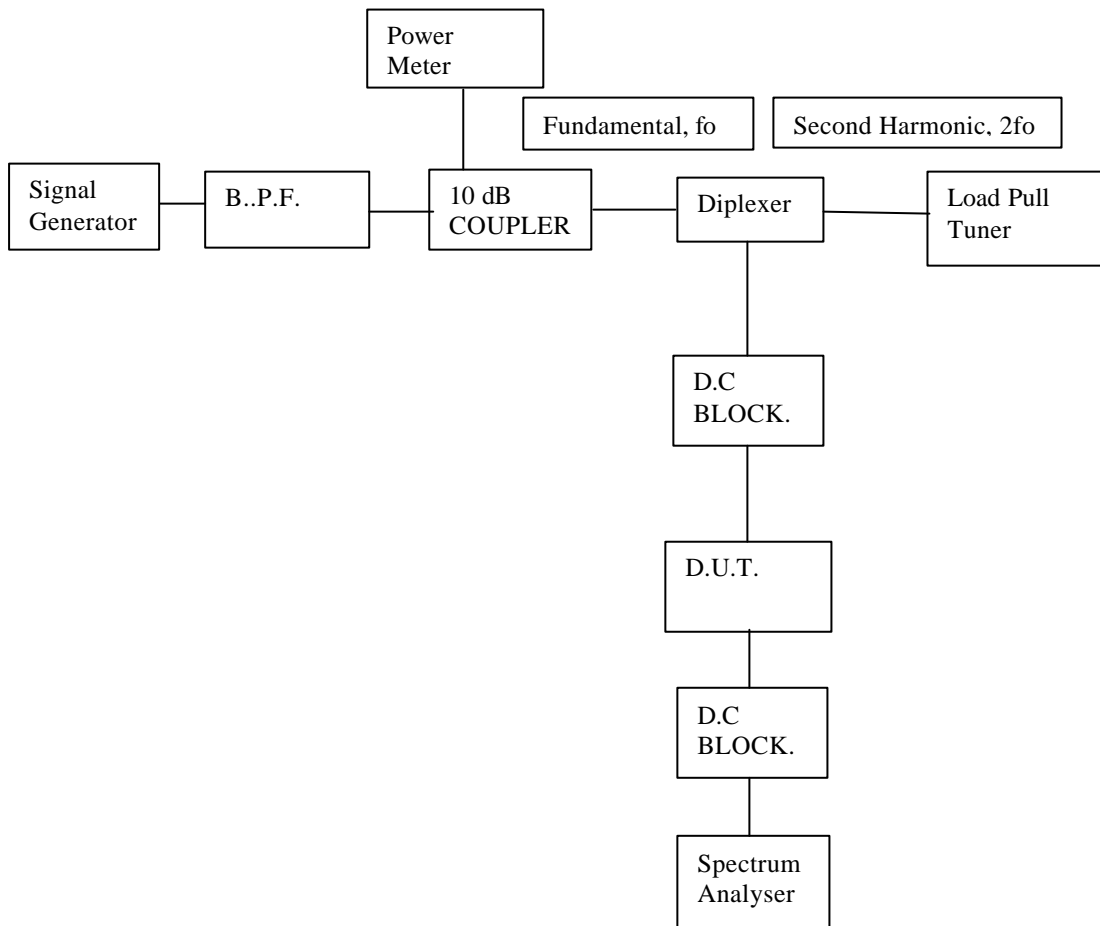
Application Note 1

Impedance Matching for Harmonic Minimisation

This note outlines the method used to find the source impedance to present to a transmit port at the second harmonic frequency ($2f_0$) to reduce the second harmonic level at the antenna.

This should be carried out for a set of devices that represent the process variants. This way a compromise can be found that suits all variants.

The necessary equipment is shown immediately below.



The device should be mounted on a PCB with 50Ω tracks running from all RF pins to SMA connectors on the PCB edge (DUT). All ports should be externally DC blocked and unused ports should be terminated in 50Ω . All measurements should be performed at the incident powers for which the harmonic levels are specified in this document.

The 2nd Harmonic level at the Antenna Port is measured using the Spectrum Analyser and the Vertical and Horizontal position of the Load Pull Stub adjusted such that this level is minimised.

The device should then be removed from the board and an SMA connector mounted such that the source impedance seen by the transmit port at $2f_0$ can be measured using a VNA.

Measurements should be de-embedded to the end of the SMA centre pin.

A network should then be designed to match the impedance of the low pass filter (LPF), which usually comes in front of the device, to the $2f_0$ source impedance that gives sufficiently reduced $2f_0$ levels for all devices measured.

The network should be designed to maintain a good match and insertion loss at the fundamental frequency.

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